

**METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING
ELECTRONIC DIE WITHIN COMPONENT PACKAGES**

TECHNICAL FIELD

The present invention relates generally to computer-aided methods and systems for manufacturing products in a high volume, automated continuous process and more particularly to improved methods and apparatus for automatically positioning electronic die within component packages.

BACKGROUND OF THE INVENTION

Integrated circuit devices are well-known in the prior art. Such devices or so-called "die" are normally designed to be supported or carried in a package having a plurality of pins or leads. The package serves as a carrier and as a heat sink and is normally square or rectangular in shape. The packages, which include a cavity in which the integrated circuit die is placed, may be formed of metal, ceramic or plastic components. After the integrated circuit is secured in the cavity of the package, a component "lid" is typically placed over an exposed surface of the circuit. A bottom surface of the lid includes a "pre-form" material such as epoxy or solder that is used to secure the lid over the circuit to provide a protective cover. The pre-form is cured by placing the package in a furnace.

Packaging unusable die which must be scrapped after testing is inefficient and costly. Accordingly, the die are often tested for continuity during the manufacturing process. This has been accomplished by placing die in temporary

packages and subjecting the assembled package to extensive testing, which includes burn-in and discrete testing. Discrete testing includes testing the devices for speed and for errors which may occur after assembly and after burn-in. Burn-in testing accelerates failure mechanisms such that devices which have the potential to fail later but which failure would not otherwise be apparent at nominal test conditions can be eliminated.

However, testing unpackaged die requires a significant amount of handling. The temporary package must not only be compatible with test and burn-in procedures, but must also secure the die without damaging the die at the bond pads or elsewhere during the process. Bonds pads are conductive areas on the face of the die which are used as an interconnect for connecting the die circuitry to the package. The positioning of the die within the cavity of the temporary package is therefore critical since the placement of the die bond pads relative to the temporary package electrical interconnects must be properly aligned in order to subject the die to such extensive testing.

Precising die packaging includes mechanically locating a component in a precise position or placement. Various "precising" methods for this purpose are known in the art. However, there have been several problems associated with such precising methods and systems. For example, it has been difficult to position the die bond pads in electrical contact

with temporary package electrical interconnects in an accurate and consistent manner so as to facilitate a high volume, continuous manufacture of temporary packages. Another disadvantage associated with the prior art is that the die is often destroyed upon contact with the temporary package. Moreover, a significant investment in the costly integrated circuit device is often lost when the positioning of the die within the temporary package is not properly aligned. Accurate placement and positioning of the die in the temporary package is thus critical to providing acceptable results.

One attempt to overcome the problems associated with the prior art has been to precise die and packages by mechanical fixturing. However, assembly tolerances used in mechanical fixturing techniques are often insufficient to prevent improper alignment. Mechanical fixturing also leads to damage of the die or temporary package. While such techniques have proven useful in improving the accuracy and reliability of the die placement, these techniques do not enable die to be precisely positioned within temporary packages in a manner that allows production efficiencies capable of supporting large volume operations.

Accordingly, there remains a long-felt need in the semiconductor industry to provide for improved methods and apparatus for manufacturing integrated circuit temporary packages in a high volume, cost-efficient and reliable manner which includes automatically positioning integrated circuit

die within the temporary packages such that die bond pads are in electrical contact with temporary package electrical interconnects to allow extensive testing to be performed.

BRIEF SUMMARY OF THE INVENTION

It is thus a primary object of the present invention to provide computer-controlled methods and apparatus for automating the positioning of integrated circuit devices or die within temporary packages utilizing a high volume, continuous process.

It is another object of the invention to provide an automated apparatus for the positioning of electronic die within temporary packages that is used in-line with other machines to facilitate formation of assembled packages which may then be subjected to continuity testing and the like.

It is yet another object of the invention to describe methods and systems for accurately positioning electronic die within temporary packages in a reliable, cost-effective manner.

It is still another object of the invention to provide methods and apparatus for continuous positioning of integrated circuit die within temporary packages in a production line while significantly reducing the percentage of die and temporary packages in which continuity is not established.

Yet another object of the invention is to provide multiple inspections of the die and temporary package prior to, during and after placement of the die within the temporary package. By inspecting the die at various stages of assembly,

die which are not properly aligned or positioned can be repositioned to maximize the number of electrical contacts between the die bond pads and temporary package electrical interconnects.

It is still another object of the invention to preferably use multiple cameras to facilitate precise placement of the die in the temporary packages in a continuous manner, thereby significantly enhancing the efficiency of the processing line and increasing the number of packages in which continuity is established.

It is still a further object of the invention to provide an apparatus for placing die in temporary packages wherein the packages are supported on carriers such as boats or trays that are conveyed along a path through a predetermined assembly/disassembly position. A carrier preferably includes a body portion and at least one side rail having a plurality of spaced openings therein. The carrier may be formed of plastic or metal. The apparatus further includes an indexing mechanism that functions to place each temporary package in the predetermined assembly/disassembly position to allow the integrated circuit die to be positioned precisely therein.

Still another object of the present invention is to provide a method and apparatus which utilizes previously stored die characteristics for a die in a known temporary package and in a known boat to disassemble electrical die and temporary packages from one another based on predetermined parameters and to classify the die appropriately.

According to more specific aspects of the present invention, an assembly system is provided to place die bond pads in electrical contact with temporary package electrical interconnects. Once the die bond pads are in contact with the electrical interconnects, the temporary package can be placed in a standard device tester and subject to extensive testing. Such testing includes burn-in testing and the like to establish various die characteristics and eliminate mortality. These characteristics, while not meant to be limiting, include the quality of the electrical contact between the die and the temporary package in addition to classifying the die in the temporary package based on speed grade characteristics.

The method and apparatus in accordance with the present invention includes a system which picks up and places a die on a die inverter. The die is then inverted and placed in view of a rough die camera, which takes a picture of the die. Using positional feedback from the rough die picture, a robot having a primary gripper with a restraining device attached thereto retrieves the die. The die is then presented to a fine die camera by the robot and multiple pictures are taken. While the die is being located by the die cameras, a process carrier containing a plurality of temporary packages is simultaneously indexed to place a temporary package in a predetermined assembly/disassembly position along a conveyor. An electrical socket is then inserted into the temporary package for continuity testing.

A rough temporary package picture is then taken of the temporary package and used to determine a rough location of the temporary package at the assembly/disassembly position. In a preferred embodiment, a laser height sensor may be used to determine the height of the temporary package at the position prior to taking fine package vision pictures in order to keep the camera in focus. A fine temporary package camera is then positioned over the selected electrical interconnects of the temporary package at the assembly/disassembly position and multiple fine temporary package pictures are also taken.

The die and restraining device are then transferred by a primary gripper to the predetermined assembly/disassembly position. The robot aligns the die and temporary package using the fine temporary package and fine die pictures, and presses the die, restraining device and package together to form an assembled package.

During the assembly process, the robot preferably drives to a minimum programmed assembly interlocking height and tests the completed assembly for continuity. If continuity is confirmed, the robot then releases the restraining device and die. If continuity is not established, the robot increments to a maximum programmed force setting. If continuity is still not established, the restraining device and die are removed from the temporary package. A new temporary package is placed in the predetermined assembly position and the fine die, rough package, and fine temporary package pictures are retaken. The

die and new temporary package are then reassembled and retested.

In an alternative embodiment of the present invention, the robot drives down until physical contact is established between the die and the temporary package. After physical contact is established, the robot drives to a minimum programmed assembly interlocking height. The primary gripper releases the die and lid or other restraining device and retracts to a waiting position. Electrical continuity of the assembly is tested. If the assembly has electrical continuity between the die and the temporary package, the process is completed. If electrical continuity is not established the primary gripper retrieves the die and restraining device and awaits instruction from the operator. The operator may choose to retry the present temporary package, utilize the next package, or purge the die from the system and use the next die.

Any electromechanical device which is capable of transferring component parts from one position to another may be used in the present invention. In a preferred embodiment, however, the transferring device is a robot arm. The apparatus has a control mechanism including a microprocessor and associated program routines that selectively control the robot arm (i) to move the primary gripper to pick up a restraining device and to a lid feeder station to pick up a lid, (ii) to move the primary gripper along with the lid and restraining device to pick up the die following photographing

by the rough die camera, (iii) to move the primary gripper along with the lid and the die to a position to be photographed by the fine die camera, and (iv) to move the lid and the die to the predetermined assembly/disassembly position located along the conveyor.

The control routines also function to return the primary gripper to the predetermined assembly position and retrieve the die and restraining device in the event that continuity is not established with the temporary package. The primary gripper then returns to select a second lid, another restraining device and a second die while the carrier is simultaneously indexed to place the next temporary package of the carrier in the predetermined assembly/disassembly position along the path. The assembly process continues in this manner.

The present invention also includes a method and apparatus for disassembling the electrical die and temporary package based on predetermined parameters or characteristics. The disassembly process occurs in a manner substantially opposite the assembly process. In particular, a carrier containing a plurality of temporary packages approaches the predetermined assembly/disassembly position. Each package contains an electrical die which has been subjected to extensive testing. The primary gripper retrieves the electrical die and inverts the die using a die inverter. A lid precursor similar to the one used for assembly is used to place the lid in a known location. The die is thus separated from the temporary package.

The foregoing has outlined some of the more pertinent objects of the present invention. These objects should be construed to be merely illustrative of some of the more prominent features and applications of the invention. Many other beneficial results can be attained by applying the disclosed invention in a different manner or modifying the invention as will be described. Accordingly, other objects and a fuller understanding of the invention may be had by referring to the following Detailed Description of the preferred embodiment.

BRIEF DESCRIPTION OF THE DRAWINGS

For a more complete understanding of the present invention and the advantages thereof, reference should be made to the following Detailed Description taken in connection with the accompanying drawings in which:

FIGURE 1A is a plan view of an assembly/disassembly system for automatically positioning die within temporary packages in accordance with the present invention;

FIGURES 1B-1C are side views of the assembly/disassembly system shown in FIGURE 1A;

FIGURES 2A-2B are side and plan views respectively of a die pack feeder for use in accordance with the present invention;

FIGURE 3A-3C are side views of a wafer handler base having a transfer mechanism which is suitable for use in the present invention;

FIGURE 4 is a side view of a rough die camera which may be used in the present invention;

FIGURES 5A-5B are front and side views of a primary gripper of a robot arm;

FIGURE 6 illustrates a clip tray feeder for use in the present invention;

FIGURES 7A-7B illustrate plan and side views respectively of a lid feeder station suitable for use in accordance with the present invention;

FIGURE 7C is an enlarged view of the lid carousel illustrated in FIGURE 7A;

FIGURES 8A-8B are plan and side views respectively of a lid precisor which is suitable for use in accordance with the present invention;

FIGURE 9 is a plan view of the various components of an indexing mechanism for use in accurately positioning the boat in the assembly/disassembly station of the apparatus;

FIGURE 10 shows a rough temporary package camera for use in accordance with the present invention;

FIGURES 11A-11B illustrate side views of a fine temporary package camera and secondary gripper which are suitable for use in accordance with the present invention;

FIGURES 12A-12B show an unclipping mechanism in a lowered position which is suitable for use in the disassembly process of the present invention; and

FIGURE 13 illustrates a secondary inverter and die precisor for use in the disassembly process of the present invention.

Similar reference characters refer to similar parts throughout the several views of the drawings.

DETAILED DESCRIPTION

The inventive method and apparatus will now be described in conjunction with the continuous positioning of integrated circuit die within temporary packages. It should be appreciated that the use of the invention for this purpose should be considered merely exemplary and that the techniques and mechanisms described herein can be used whenever it is desired to accurately position, bond or attach dies.

In an exemplary embodiment, a method and apparatus are provided for automatically positioning die within temporary packages to facilitate extensive testing. As shown in FIGURE 1A, the apparatus 10 generally includes surface 42, a programmable robot arm 12 which preferably includes three arms 12a, 12b and 12c, wafer feeder station 14, die inverter 16, rough die camera 24, a lid feeder station 22, lid precisor 26, fine die camera 30, a predetermined assembly/disassembly position 28, a clip tray feeder 50, and rough and fine temporary package cameras (not shown in FIGURE 1A). The assembly/disassembly position 28 is located along a conveyor 36 that conveys a carrier along a linear path indicated by arrow 34 between a first position, corresponding to inlet 38,

and a second position, corresponding to outlet 40. The die, restraining device and temporary package are assembled at assembly/disassembly position 28 as will be described more fully herein.

It should be appreciated that each carrier enters the apparatus at the inlet 38 and then travels along the path through the assembly/disassembly position 28 where the die are positioned within the packages in the carrier. The continuity between the die and temporary package is preferably evaluated at assembly/disassembly position 28. Thereafter, the carrier is conveyed through the outlet 40 and the die is then subjected to additional testing.

Although not shown in detail in FIGURE 1A, it is desired that a plurality of carriers, each supporting a number of temporary packages, be continuously supplied to conveyor 36. While not meant to be limiting, this can be accomplished by the use of a carrier input elevator 38a and carrier output elevator 40a. A new carrier is supplied at the inlet after all packages in a previous boat located at the assembly/disassembly position 28 have been indexed through predetermined position 28. Die and restraining devices such as lids and/or clips are then supplied to the packages in the new carrier. Appropriate sensor and indexing assemblies are located at the inlet 38 and outlet 40 of the conveyor 36 to control the movement of carrier thereon.

Conveyors, such as those manufactured by Flexible Technology located in Richardson, Texas, are suitable for use in the present invention. Other conveyors, such as flat belt conveyors, timing belt conveyors, walking beam mechanisms and the like are also suitable for use in the present invention. The conveyor is controlled by a suitable electric motor and gearing mechanism as is well-known in the art.

As described generally above, a plurality of cameras are used in accordance with the present invention to insure precise placement of die within temporary packages. While not meant to be limiting, one embodiment of the present invention utilizes five cameras or image producers. As will become apparent, a first camera is used to accurately locate the initial position of a wafer and individual die before the die is moved. Two additional cameras are used to locate the die and the remaining two cameras are used to locate the temporary package or device under testing (hereinafter "DUT"). The present invention uses rough cameras to locate the die and DUT's general positions such that the die and DUT can each be positioned in the respective fine camera's fields of view. Preferably, the fine cameras have fields of view in the range of about 0.0020". In an alternative embodiment, three cameras are utilized, namely, a first camera to accurately locate the position of a wafer and individual die, a die camera and a temporary package camera.

The basic operating method of the automatic die placement apparatus can now be described. Referring now to FIGURES 1A-1C, in which an assembly system 10 for automatically positioning die within temporary packages in accordance with the present invention is shown. Wafers, which have been previously tested to select die from a wafer map or ink dot, are positioned in wafer feeder station 14. The wafers may have previously been divided into individual die. Alternatively, singulated die may be supplied to wafer feeder station 48a-48c.

FIGURES 2A-2B illustrate side views of a 2x2" die pack feeder 48b. The die pack feeder 48b include die pack input 60 and output 64, die shuttle 62 and pneumatic cylinder 64. Alternatively, a 4x4" die pack feeder may be used or as shown in FIGURE 1A, a 2x2" die pack feeder 48b and a 4x4" die pack feeder 48a may be utilized. Die pack feeders 48b are particularly suitable for use in the invention when singulated die are supplied to apparatus 10. Packs are placed into input 60 and one pack is then moved onto shuttle 62 by pneumatic cylinder 64 into the workcell. Die are then placed into or taken out of the packs. When the process is completed, shuttle 62 is moved by pneumatic cylinder 64 to output station 66.

Alternatively, a wafer handler base 170 as illustrated in FIGURES 3A-3C may be used when the die are supplied in wafer form. First camera 20 as shown in FIGURE 1A is preferably

positioned over location 18. Location 18 corresponds to a die transfer position. First camera 20 is preferably located to look down at the film frame and wafer. First camera 20 first determines the exact position of the wafer on the film frame by looking for combi marks or fiducial marks on the wafer. The camera then takes a picture of each die to verify that the die is there, verify that there is no ink dot on the die, and to locate the die's exact position to account for any change in position when the film frame is stretched.

Die transfer arm 70 shown in FIGURES 3A-3C of the present invention picks up a die from location 18 and places the die on die inverter 16. The die is then inverted by die inverter 16, placed on die pedestal 74 and brought into view of rough die camera 24. While not meant to be limiting, die is picked off of wafer handler base 170 or die pack feeder 48b using vacuum quills and pneumatic cylinders. The cylinders are reciprocated in such a manner that the die is transported and placed on die inverter 16.

Rough die camera 24 is preferably located on surface 42 behind lid feeder station 22. As shown in FIGURE 4, rough die camera 24 includes a CCD (Charge Coupled Device) camera 80, lens 82 and prism 72. Rough die camera 24, which is preferably located behind feeder station 22, looks up at the die through prism 72 at die inverter 16 to determine the general position or location of the die so that robot 12 using gripper 52 may place the die within the field of view of fine

die camera 30. Prior to rough die camera 24 taking a picture, the die is preferably illuminated with backlighting. Rough die camera 24 then takes a picture of the die at inverter station 22.

The rough die picture is analyzed utilizing a computer program to determine the rough position of the die. A blob finder is used to locate the centroid of the die, which is held on the pedestal arm 74. The blob finder analyzes the binary (black/white) picture of the die and pedestal. Based on the position of the centroid, an edge finding ruler is utilized in the negative Y direction (away from the pedestal arm) in order to locate the bottom edge of the die, as referenced in the vision window. A line finding box is then used at the bottom edge of the die to locate the angle of the bottom die edge.

The die size is preferably known and stored in the data file (IGES format in particular) associated with the die. An edge finding ruler is utilized in the negative X direction relative to the vision window. The edge finding ruler starts in the centroid of the die and is used to locate an edge of the die perpendicular to the edge located above. A line finding box is used at the perpendicular edge to locate the angle of the side edge. Once the angle and location of two perpendicular sides of the die is determined, two edge finding rulers are placed over the image. One ruler is placed across the die in order to measure the width of the die. The second

ruler is placed perpendicular to the first ruler to find the length of the die to determine the exact size of the die. The center position of the die is calculated, using the average of the angles obtained above.

Using positional feedback data from the computer and rough die picture, robot 12 then orients primary gripper 52 to the die. As shown in FIGURES 5A-5B, primary gripper preferably includes vacuum quill 90, linear slide 92 and suction cups 92. Primary gripper 52, which has a restraining device attached thereto, retrieves the die. While not meant to be limiting, the restraining device may be a bridge clip, a clip and lid, screw or combination thereof. When lids are used with clips as the restraining device, lid transfer arm 54 shown in FIGURES 7A-7B selects a lid from lid feeder station 22 and presents the lid to mechanical precisor 26. Lid precisor 22 is used to place lids in a known location.

In a preferred embodiment, lid feeder station 22 supports a plurality of lids in multiple stacks on a rotatable carousel 100 shown in FIGURE 7A. As the lids are exhausted from each stack in the carousel, the carousel 100 rotates to present a new stack to the lid transfer arm 54. When all stacks of the carousel 100 are exhausted, the carousel 100 may be rotated away from the lid transfer arm 54 and a new carousel provided.

FIGURES 7A-7B illustrate lid feeder station 22 while FIGURE 7C depicts a plan view of a lid carousel 100 for use in the present invention.

As mentioned above, lid transfer arm 54 selects a lid from lid feeder station 22 and presents the lid to lid precisor 26. FIGURE 8A illustrates a plan view of lid precisor 26 while FIGURE 8B depicts a side view of lid precisor 26. Lid precisor 26 includes a vacuum chuck 110, pneumatic cylinder 112 and precisor block 114.

The clip secures the die in the temporary package during testing. Clips, which may have various configurations, provide physical connection of the tops of the temporary packages to the bottoms thereof. FIGURE 6 illustrates a clip tray feeder which is suitable for use in the present invention. More specifically, clip tray feeder 50 preferably includes an elevator 120 which carries a stack of clip trays for presentation to the machine. Each tray is individually removed and pulled into the robot's work volume by the tray presentation arms (not shown). The clip tray feeder 50 will utilize different styles of clips by utilizing optional clip trays. The restraining device may include a clip and die, a clip, lid and die or a clip/lid combination which are formed as a unit and used in conjunction with a die. Preferably, however, the clip is picked up by the primary gripper 52 before the lid or die. The lid is placed on the vacuum chuck 110 shown in FIGURES 8A and 8B. The lid is placed on the vacuum chuck 110. The pneumatic cylinder is actuated, pressing the precisor block 114 against the lid. This action puts the lid into a location that is "known" to robot 12. It

should be appreciated that the present invention is not limited to a restraining device which includes clips and lids. Any method of restraint is possible. For example, screws, adhesives or the like may be substituted or used in addition to clips.

In an alternative embodiment, the restraining device need not be picked up. Rather, the restraining device may be attached to or be an integral part of the temporary package.

After the die has been picked up by the primary gripper 52, the die is then presented to fine die camera 30. Fine die camera 30 is preferably located on base 42 near conveyor 36 so that it looks sideways through a prism, up at the die. The base 42 of apparatus 10 may be constructed of metal, granite or a vibration isolation table. Base 42, however, is preferably formed of granite. A granite base provides stability, which is critical for precision and accuracy. Fine die camera 30 determines the precise location of the die and takes multiple pictures of the die such that the die bond pads and electrical interconnects can be properly aligned.

More specifically, the die is secured and opposite corners of the die are presented to the fine die camera 30. The following algorithm describes the analysis done for each corner of the die. First, a picture of the die corner is taken. The binary picture is used for all subsequent analysis steps. Two edge finding rulers are positioned across the width and height of the screen in order to locate the edges of

the die features (Vbb ring, bond pad, etc.) specified. Once the two edges are located, line finding boxes are placed at the transition points of the edges of the die features. These are used to locate the angle of the die corner. The angles and points are used to mathematically calculate the corner point of the die etching in the field of view of the camera. The X and Y position of the corner point is the only information used from the fine die picture.

Once the die X and Y points of two opposite corners are known, two additional pictures are taken in order to precisely determine the angle of the die. The pictures are taken by placing two opposite features of the die in front of the camera. The features are on the same side of the die, however. By locating two points of the etching along the same side of the die, the angle of the die relative to the angle of the gripper can be calculated.

A picture is taken and the binary picture is used for all subsequent analysis steps. An edge finding ruler is utilized from the top of the vision window in the negative Y direction in order to locate the etching of the die. At the point where the etching is located, a line finding box is placed across the screen, perpendicular to the edge finding ruler in order to verify that the edge of the die has been located. This information is later used to position the die in proper alignment with the temporary packages.

**CLAIMS:**

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What is claimed is:

1. A method, using a programmable robot having a plurality of arms, one of the arms having a primary gripper attached thereto for automatically positioning electronic die within temporary packages for testing, the primary gripper having a restraining device attached thereto and wherein at least one temporary package is supported on a boat, comprising the steps of:

(a) conveying a first boat along a path between a first position and a second position;

(b) removing a die from a wafer feeder station utilizing a die transfer arm and moving the die to a die inverter;

(c) inverting the die at the die inverter;

(d) taking a picture with the die in the inverted position;

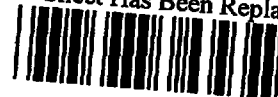
(e) removing a first lid from a lid feeder station using a lid transfer arm;

(f) reciprocating the lid transfer arm between first and second positions to thereby transfer the first lid from the lid feeder station to a lid precisor;

(g) placing the lid in a known location using the lid precisor;

(h) moving the primary gripper and lid from the lid precisor to the die inverter and picking up the inverted die;

(i) taking a second picture of the lid and die to determine the precise location of the die;





(j) taking a picture of a temporary package in the boat to determine the general position of the temporary package in the boat;

(k) using the position determined in step (j) and taking at least one picture of the temporary package; and

(l) aligning the die and temporary package utilizing the pictures to assemble the die and temporary package into an assembled package in the boat for testing.

2. The method as described in Claim 1 further including the steps of:

(m) releasing the primary gripper and returning the primary gripper to the position in step (h);

(n) indexing the boat to place a second temporary package in the predetermined assembly position along the path; and

(o) repeating steps (b)-(n) for a predetermined period.

3. The method as described in Claim 1 further including the step of:

taking a picture of the die prior to the die being transferred to the die inverter to verify that the die has no ink dot thereon and to locate the die's position.

4. The method as described in Claim 1 further including the step of:



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picking up a clip with the primary gripper prior to picking up the inverted die from the die inverter.

5. The method as described in Claim 1 wherein the step of assembling the package includes:

driving the robot to a predetermined minimum programmed assembly locking height;

assembling the die within the temporary package;

testing the completed assembly for continuity;

releasing the primary gripper if continuity is established;

incrementing the robot if continuity is not established to a maximum programmed force setting and retesting for continuity;

releasing the primary gripper if continuity is established;

removing the lid and die if continuity is not established, and positioning a second temporary package in the predetermined assembly position; and

retaking pictures using the second, third and fourth image producers and reassembling the package.

6. The method as described in Claim 1 wherein the step of assembling the package includes:

driving the robot until a physical contact is established between the die and temporary package;

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driving the robot to a minimum programmed assembly interlocking height;

releasing the lid and die from the primary gripper such that the lid and die are positioned within the temporary package thereby forming an assembled package while the primary gripper is retracted to a waiting position; and

testing the assembled package for continuity and if continuity is not established, the primary gripper retrieves the die and lid and awaits for further prompting.

7. A method, using a programmable robot having a plurality of arms, one of the arms having a primary gripper attached thereto for disassembling electronic die positioned within temporary packages for testing, the primary gripper having a restraining device attached thereto and wherein at least one temporary package is supported on a boat, comprising the steps of:

- (a) conveying a first boat along a path between a first position and a second position;
- (b) removing a die from a temporary package utilizing the primary gripper and moving the die to a disassembly die;
- (c) inverting the die at the disassembly die inverter such that the die is face up;
- (d) placing the lid on a lid precisor;
- (e) retrieving the face up die;
- (f) disposing the die into a predetermined output device;



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(g) reciprocating a lid transfer arm between second and first positions to thereby transfer the first lid from the lid precisor station to a lid carousel;

(h) releasing the primary gripper and returning the primary gripper to the position in step (b); and

(i) indexing the boat to place a second temporary package in the predetermined assembly position along the path.

8. The method as described in Claim 7 further including repeating steps (b)-(i) for a predetermined period.

9. Apparatus for automatically positioning a die having die bond pads within a temporary package for testing using a lid, wherein at least one temporary package is supported on a boat, comprising:

a programmable robot having a plurality of arms, one of the arms having a primary gripper attached thereto;

a wafer feeder station;

a die inverter for inverting a die;

a transporter for conveying a die from the wafer feeder station to the die inverter;

an image producer for taking a picture of the inverted die;

a lid feeder station;

a lid precisor;

a second transporter for picking up a lid from the lid feeder station and moving the lid to the lid precisor;



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a third transporter for reciprocating the primary gripper to pick up the lid from the lid precursor and move the lid to the die inverter and pick up the inverted die;

a second image producer for taking a picture of the lid and the die;

a fourth transporter for conveying a first boat along a path such that a temporary package in the boat is stationed at a predetermined assembly position;

a third image producer for taking a picture of the temporary package at the predetermined assembly position to determine a general position of the temporary package;

a fourth image producer for taking a picture of the temporary package to determine the precise location of the temporary package at the predetermined assembly position;

a transferring device for moving the lid and die to the predetermined assembly position; and

a positioner for aligning the die bond pads of the die with the temporary package and assembling the lid and die within the temporary package to test for continuity.

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